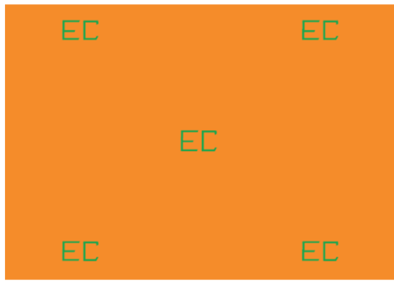


ETL-XPC-601
(N TYPE)
(For HB Grade Laminate)

■特性

- 非難燃性類型材料
- 尺寸變化、彎曲度小
- 優越的打孔性
- 符合 UL 746E 規範及 RoHS 要求
- 中國製造

■CHARACTERS

- Universal material for non-flame retardant
- Dimensional change and warpage are small
- Excellent pnuchability
- Meet UL 746E and conform to the request of RoHS
- Made in China

■用途 APPLICATIONS

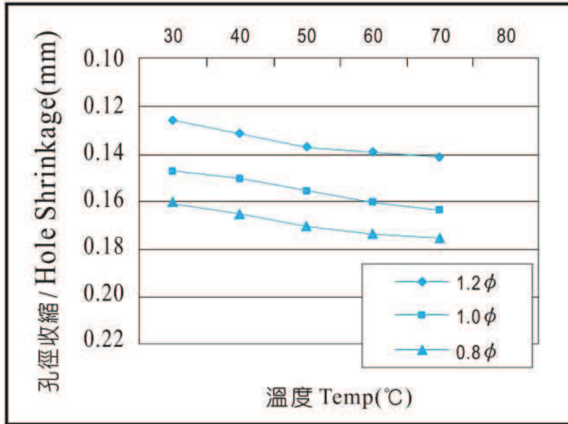
- 收音機、收錄音機、時鐘、數字處理機、電腦鍵盤等。
  Radios, Radio-cassette recorder/players, Clocks, Word processor, Personal computer keyboards, etc.

■一般物性 GENERAL PROPERTIES

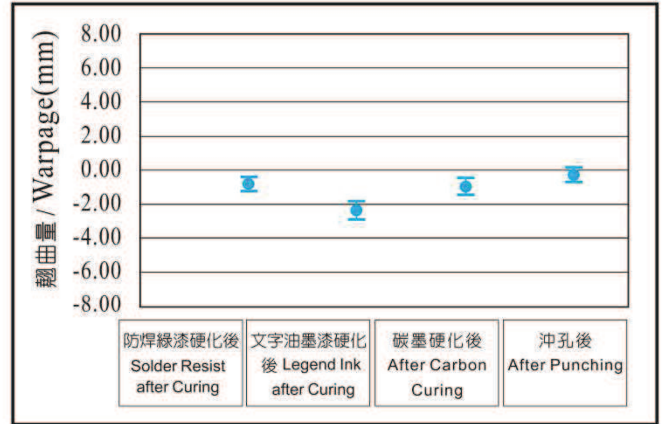
試驗項目 Test Item		單位 Unit	處理條件 Condition	品管規格值 Guarantee Value	實測標準值 Standard Value
體積阻抗 Volume Resistivity		Ω-cm	C-96/20/65	Above 1 X 10^{12}	1 X 10^{12}~1 X 10^{13}
			C-96/20/65+C-96/40/90	Above 1 X 10^{11}	5 X 10^{11}~5 X 10^{12}
表面阻抗 Surface Resistance	接著劑面 Adhesive Surface	Ω	C-96/20/65	Above 1 X 10^{10}	1 X 10^{11}~1 X 10^{12}
			C-96/20/65+C-96/40/90	Above 1 X 10^{9}	1 X 10^{10}~1 X 10^{11}
	積層板面 Laminate Surface		C-96/20/65	Above 1 X 10^{9}	5 X 10^{9}~5 X 10^{11}
			C-96/20/65+C-96/40/90	Above 1 X 10^{8}	5 X 10^{8}~5 X 10^{9}
絕緣阻抗 Insulation Resistance		Ω	C-96/20/65	Above 1 X 10^{10}	1 X 10^{11}~1 X 10^{12}
			C-96/20/65+D-2/100	Above 1 X 10^{7}	5 X 10^{7}~5 X 10^{8}
介電常數(1 MHz) Dielectric Constant		–	C-96/20/65	Less than 5.5	4.3~5.0
			C-96/20/65 +D-24/23	Less than 6.0	5.3~5.8
散發因子(1 MHz) Dissipation Factor		–	C-96/20/65	Less than 0.05	0.035~0.046
			C-96/20/65 +D-24/23	Less than 0.08	0.050~0.060
焊錫耐熱性(260℃) Solder Heat Resistance		sec	A	Above 10	30~40
銅箔剝離強度 Peel Strength	銅箔(35μm) Copper Foil	kgf/cm	A	Above 1.5	1.80~2.20
			S (260℃, 10 sec)	Above 1.5	1.80~2.20
彎曲強度 Flexural Strength		kgf/mm^2	A	Above 10	12~16
吸水率 Water Absorption		%	E-24/50+D-24/23	Less than 1.8	1.00~1.30
耐熱性 Heat Resistance		–	A	190℃ 30 min no blistering	190~195℃ 30 min no blistering
難燃性 Flame Resistance (UL 94 method)		sec	A& E-168/70	94 HB	94 HB
耐藥品性 Alkali Resistance		–	Immersion in 3% NaOH 40℃ (3 mins)	無異常 No abnormality	無異常 No abnormality
加工沖孔性 Punchability		–	A	Suitable temp. 50~70 ℃	GOOD
耐漏電破壞性 CTI (IEC 60112)		Volt	A	≧600	≧600

◎以上數據試片厚度 1.6mm (Note : Test specimen thickness is 1.6mm)

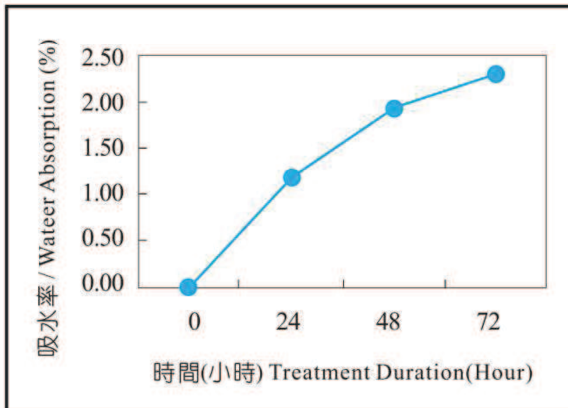
■打孔後孔徑收縮
Hole Shrinkage after Punching



■刷電路板加工時之彎曲
Wrpage During Process



■板材吸水率經時試驗
Moisture Absorption



■焊錫中耐熱之溫度特性
Characteristic of Solder Heat Resistance